

Dual D-Type Flip-Flop with Set and Clear With 5V-Tolerant Inputs

The MC74LVX74 is an advanced high speed CMOS D-type flip-flop. The inputs tolerate voltages up to 7V, allowing the interface of 5V systems to 3V systems.

The signal level applied to the D input is transferred to O output during the positive going transition of the Clock pulse.

Clear (\overline{CD}) and Set (\overline{SD}) are independent of the Clock (CP) and are accomplished by setting the appropriate input Low.

- High Speed: $f_{max} = 145\text{MHz}$ (Typ) at $V_{CC} = 3.3\text{V}$
- Low Power Dissipation: $I_{CC} = 2\mu\text{A}$ (Max) at $T_A = 25^\circ\text{C}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise: $V_{OLP} = 0.5\text{V}$ (Max)
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300mA
- ESD Performance: HBM > 2000V; Machine Model > 200V

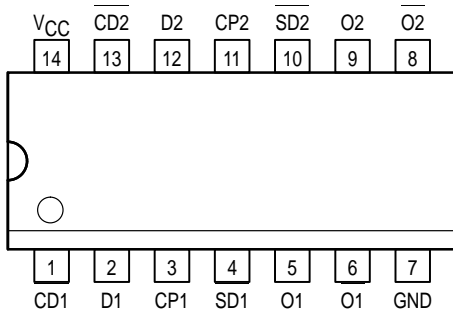



Figure 1. 14-Lead Pinout (Top View)


MC74LVX74

LVX

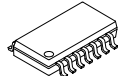
LOW-VOLTAGE CMOS



D SUFFIX
14-LEAD SOIC PACKAGE
CASE 751A-03



DT SUFFIX
14-LEAD TSSOP PACKAGE
CASE 948G-01



M SUFFIX
14-LEAD SOIC EIAJ PACKAGE
CASE 965-01

PIN NAMES

Pins	Function
CP1, CP2	Clock Pulse Inputs
D1, D2	Data Inputs
$\overline{CD1}$, $\overline{CD2}$	Direct Clear Inputs
$\overline{SD1}$, $\overline{SD2}$	Direct Set Inputs
O _n , O _n	Outputs



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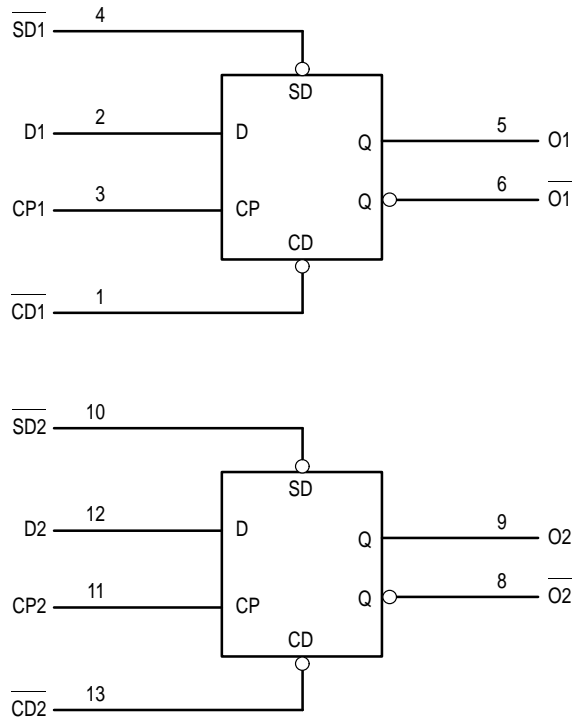


Figure 2. Logic Diagram

INPUTS				OUTPUTS		OPERATING MODE
SDn	CDn	CPn	Dn	On	On	
L	H	X	X	H	L	Asynchronous Set
H	L	X	X	L	H	Asynchronous Clear
L	L	X	X	H	H	Undetermined
H	H	↑	h	H	L	Load and Read Register
H	H	↑	l	L	H	
H	H	↕	X	NC	NC	Hold

H = High Voltage Level; h = High Voltage Level One Setup Time Prior to the Low-to-High Clock Transition; L = Low Voltage Level; l = Low Voltage Level One Setup Time Prior to the Low-to-High Clock Transition; NC = No Change; X = High or Low Voltage Level or Transitions are Acceptable; ↑ = Low-to-High Transition; ↕ = Not a Low-to-High Transition; For I_{CC} Reasons DO NOT FLOAT Inputs

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{in}	DC Input Voltage	-0.5 to +7.0	V
V _{out}	DC Output Voltage	-0.5 to V _{CC} +0.5	V
I _{IJK}	Input Diode Current	-20	mA
I _{OK}	Output Diode Current	±20	mA
I _{out}	DC Output Current, per Pin	±25	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±50	mA
P _D	Power Dissipation	180	mW
T _{stg}	Storage Temperature	-65 to +150	°C

* Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	3.6	V
V _{in}	DC Input Voltage	0	5.5	V
V _{out}	DC Output Voltage	0	V _{CC}	V
T _A	Operating Temperature, All Package Types	-40	+85	°C
Δt/ΔV	Input Rise and Fall Time	0	100	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V _{CC} V	T _A = 25°C			T _A = -40 to 85°C		Unit
				Min	Typ	Max	Min	Max	
V _{IH}	High-Level Input Voltage		2.0	1.5			1.5		V
			3.0	2.0			2.0		
			3.6	2.4			2.4		
V _{IL}	Low-Level Input Voltage		2.0			0.5		0.5	V
			3.0			0.8		0.8	
			3.6			0.8		0.8	
V _{OH}	High-Level Output Voltage (V _{in} = V _{IH} or V _{IL})	I _{OH} = -50μA I _{OH} = -50μA I _{OH} = -4mA	2.0	1.9	2.0		1.9		V
			3.0	2.9	3.0		2.9		
			3.0	2.58			2.48		
V _{OL}	Low-Level Output Voltage (V _{in} = V _{IH} or V _{IL})	I _{OL} = 50μA I _{OL} = 50μA I _{OL} = 4mA	2.0		0.0	0.1		0.1	V
			3.0		0.0	0.1		0.1	
			3.0			0.36		0.44	
I _{in}	Input Leakage Current	V _{in} = 5.5V or GND	3.6			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	V _{in} = V _{CC} or GND	3.6			2.0		20.0	μA

MC74LVX74

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0\text{ns}$)

Symbol	Parameter	Test Conditions	$T_A = 25^\circ\text{C}$			$T_A = -40 \text{ to } 85^\circ\text{C}$		Unit
			Min	Typ	Max	Min	Max	
t_{PLH} , t_{PHL}	Propagation Delay CP to O or O	$V_{CC} = 2.7\text{V}$ $C_L = 15\text{pF}$		7.3	15.0	1.0	18.5	ns
		$V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 50\text{pF}$		9.8	18.5	1.0	22.0	
t_{PLH} , t_{PHL}	Propagation Delay SD or CD to O or O	$V_{CC} = 2.7\text{V}$ $C_L = 15\text{pF}$		8.4	15.6	1.0	18.5	ns
		$V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 50\text{pF}$		10.9	19.1	1.0	22.0	
f_{max}	Maximum Clock Frequency (50% Duty Cycle)	$V_{CC} = 2.7\text{V}$ $C_L = 15\text{pF}$	55	135		50		MHz
		$V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 50\text{pF}$	45	60		40		
t_{OSHL} , t_{OSLH}	Output-to-Output Skew (Note 1.)	$V_{CC} = 2.7\text{V}$ $C_L = 50\text{pF}$			1.5		1.5	ns
		$V_{CC} = 3.3 \pm 0.3\text{V}$ $C_L = 50\text{pF}$			1.5		1.5	

1. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

TIMING REQUIREMENTS (Input $t_r = t_f = 3.0\text{ns}$)

Symbol	Parameter	V_{CC} V	Guaranteed Limit		Unit
			$T_A = 25^\circ\text{C}$	$T_A = -40 \text{ to } 85^\circ\text{C}$	
t_w	Minimum Pulse Width, CP	2.7V 3.3V ± 0.3	8.5 6.0	10.0 7.0	ns
t_w	Minimum Pulse Width, CD or SD	2.7V 3.3V ± 0.3	8.5 6.0	10.0 7.0	ns
t_{su}	Minimum Setup Time, D to CP	2.7V 3.3V ± 0.3	8.0 5.5	9.5 6.5	ns
t_h	Minimum Hold Time, D to CP	2.7V 3.3V ± 0.3	0.5 0.5	0.5 0.5	ns
t_{rec}	Minimum Recovery Time, SD or CD to CP	2.7V 3.3V ± 0.3	6.5 5.0	7.5 5.0	ns

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	$T_A = 25^\circ\text{C}$			$T_A = -40 \text{ to } 85^\circ\text{C}$		Unit
		Min	Typ	Max	Min	Max	
C_{in}	Input Capacitance		4	10		10	pF
C_{PD}	Power Dissipation Capacitance (Note 2.)		25				pF

2. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}/2$ (per flip-flop). C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

NOISE CHARACTERISTICS (Input $t_r = t_f = 3.0\text{ns}$, $C_L = 50\text{pF}$, $V_{CC} = 3.3\text{V}$, Measured in SOIC Package)

Symbol	Characteristic	$T_A = 25^\circ\text{C}$		Unit
		Typ	Max	
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	0.3	0.5	V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	-0.3	-0.5	V
V_{IHD}	Minimum High Level Dynamic Input Voltage		2.0	V
V_{ILD}	Maximum Low Level Dynamic Input Voltage		0.8	V

SWITCHING WAVEFORMS

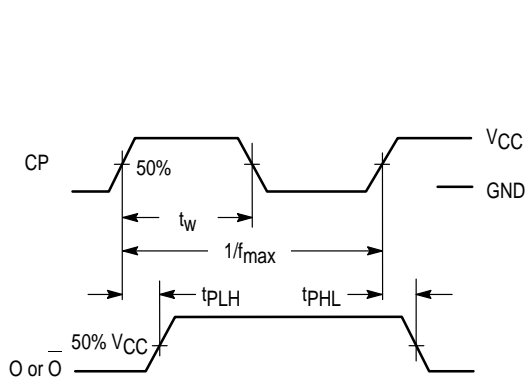


Figure 3.

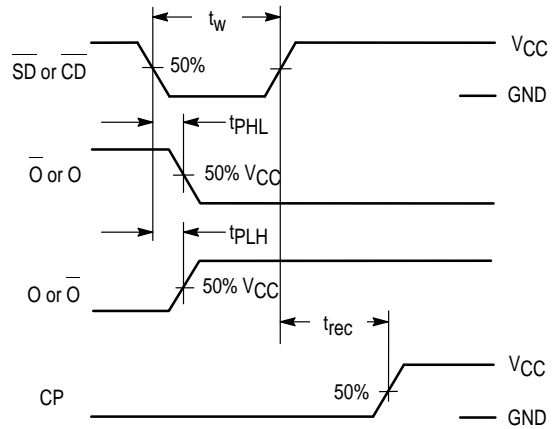


Figure 4.

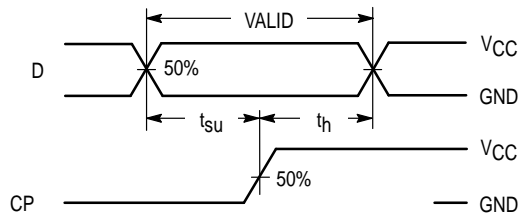
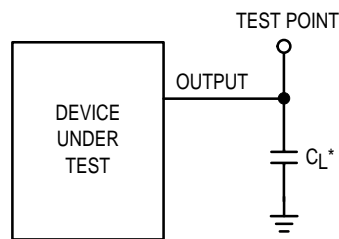


Figure 5.

TEST CIRCUIT

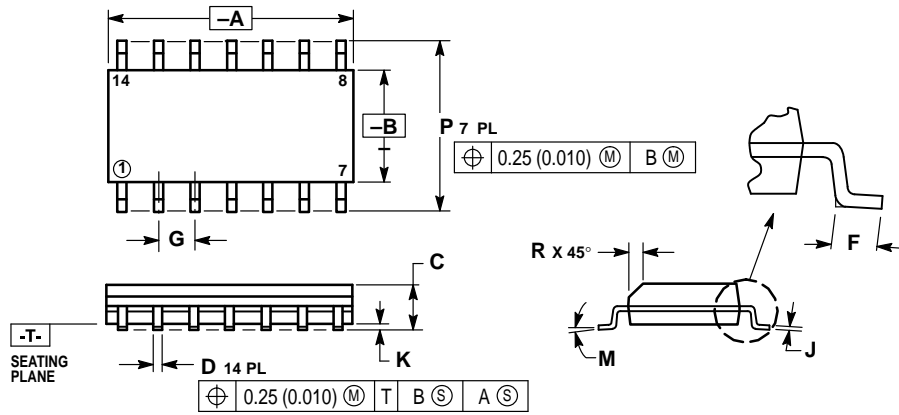


* Includes all probe and jig capacitance

Figure 6.

OUTLINE DIMENSIONS

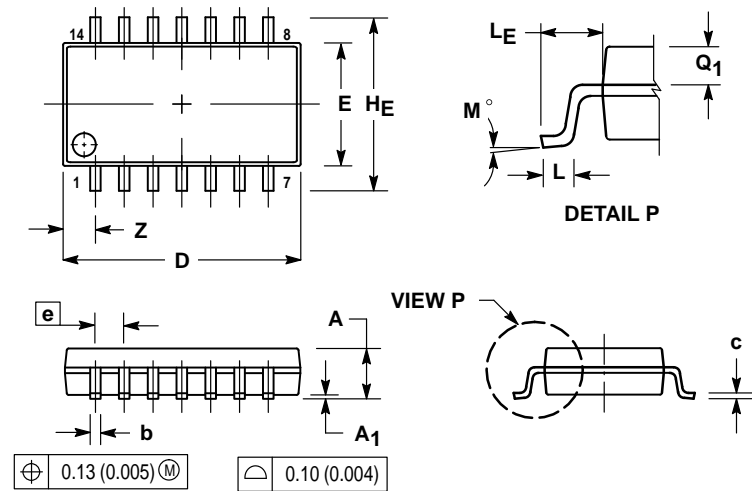
D SUFFIX
 PLASTIC SOIC PACKAGE
 CASE 751A-03
 ISSUE F



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

M SUFFIX
 PLASTIC SOIC EIAJ PACKAGE
 CASE 965-01
 ISSUE O

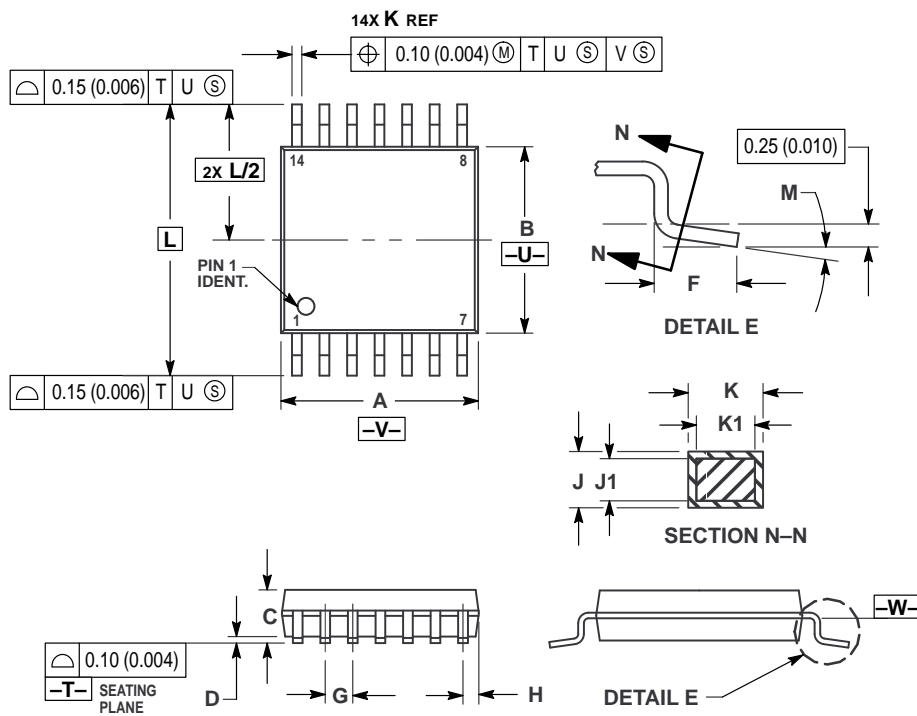


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q1	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

OUTLINE DIMENSIONS

DT SUFFIX
 PLASTIC TSSOP PACKAGE
 CASE 948G-01
 ISSUE O



- NOTES:
- 1 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - 2 CONTROLLING DIMENSION: MILLIMETER.
 - 3 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 - 4 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 - 5 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 - 6 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 - 7 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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